

Preface

ICNFCM2017 aims to present the latest research and results of scientists (academicians, PhD Students and engineers) related to the science and technology of Nano-materials including Multifunctional Composite Materials, Polymers, Ceramics and Functional materials. This conference provides opportunities for the different areas delegates to exchange new ideas and application experiences face to face, to establish business or research relations and to find global partners for future collaboration.

All papers were accepted through a peer-review process by the conference program committee and international reviewers. The selected papers contributions to be presented as lectures will make an exciting technical program. And the conference program is extremely rich, featuring high-impact presentation. We hope that the conference results constituted significant contribution to the knowledge in these up to date scientific field.

Finally, we wish all the authors and attendees of ICNFCM2017 a unique, rewarding and enjoyable memory at ICNFCM2017 in Hong Kong. We look forward to your participation in the 2nd ICNFCN 2018 in 2018.

With our warmest regards,

Conference Organizing Chair

Hariati Taib

Universiti Tun Hussein Onn Malaysia

July 2017

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